

# 3A, 50V - 1000V Surface Mount Rectifier

#### **FEATURES**

- Glass passivated chip junction
- Ideal for automated placement
- Low forward voltage drop
- High surge current capability
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

ΛD	DI	ICA	TI	O	NC
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- Switching mode power supply (SMPS)
- Adapters
- Lighting application
- Converter

#### **MECHANICAL DATA**

- Case: DO-214AA (SMB)
- Molding compound meets UL 94V-0 flammability rating
- Part no. with suffix "H" means AEC-Q101 qualified
- Packing code with suffix "G" means green compound (halogen-free)
- Moisture sensitivity level: level 1, per J-STD-020
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: As marked
- Weight: 0.09 g (approximately)

KEY PARAMETERS						
PARAMETER	UNIT					
I <sub>F(AV)</sub>	3	Α				
$V_{RRM}$	50 - 1000	>				
I <sub>FSM</sub>	80	Α				
T <sub>J MAX</sub>	150	°C				
Package	DO-214AA (SMB)					
Configuration	Single Die					





DO-214AA (SMB)

PARAMETER	SYMBOL	S3AB	S3BB	S3DB	S3GB	S3JB	S3KB	S3MB	UNIT
Marking code on the device		S3AB	S3BB	S3DB	S3GB	S3JB	S3KB	S3MB	
Repetitive peak reverse voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Reverse voltage, total rms value	V <sub>R(RMS)</sub>	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Forward current	I <sub>F(AV)</sub>				3				Α
Surge peak forward current, 8.3 ms single half sine-wave superimposed on rated load per diode	I <sub>FSM</sub>	80				А			
Junction temperature	TJ	- 55 to +150			°C				
Storage temperature T <sub>STG</sub>			- 55 to +150				°C		

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THERMAL PERFORMANCE						
PARAMETER	SYMBOL	LIMIT	UNIT			
Junction-to-lead thermal resistance	$R_{\Theta JL}$	10	°C/W			

ELECTRICAL SPECIFICATIONS (T <sub>A</sub> = 25°C unless otherwise noted)							
PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT		
Forward voltage per diode (1)	I <sub>F</sub> = 3A,T <sub>J</sub> = 25°C	V <sub>F</sub>	-	1.15	V		
D	T <sub>J</sub> = 25°C	I <sub>R</sub>	-	10	μΑ		
Reverse current @ rated V <sub>R</sub> per diode <sup>(2)</sup>	T <sub>J</sub> = 125°C		-	250	μA		
Junction capacitance	1 MHz, V <sub>R</sub> =4.0V	CJ	40	-	pF		
Reverse recovery time	I <sub>F</sub> =0.5A , I <sub>R</sub> =1.0A I <sub>RR</sub> =0.25A	+	1500	_	ne		
Neverse recovery unite	I <sub>RR</sub> =0.25A	t <sub>rr</sub>	1500		ns		

#### Notes:

- 1. Pulse test with PW=0.3 ms
- 2. Pulse test with PW=30 ms

ORDERING INFORMATION							
PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX(*)	PACKAGE	PACKING		
S3xB (Note 1)	Н	R5	O	SMB	850 / 7" Plastic reel		
		R4		SMB	3,000 / 13" Paper reel		
		M4		SMB	3,000 / 13" Plastic reel		

## Note:

- 1. "x" defines voltage from 50V (S3AB) to 1000V (S3MB)
- \*: Optional available

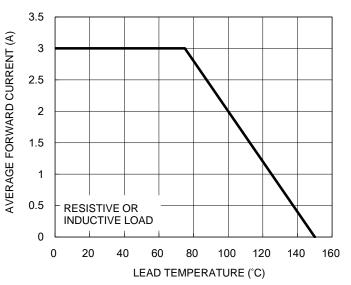
EXAMPLE P/N						
EXAMPLE P/N	PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION	
S3ABHR5G	S3AB	Н	R5	G	AEC-Q101 qualified Green compound	



#### **CHARACTERISTICS CURVES**

(T<sub>A</sub> = 25°C unless otherwise noted)

**Fig.1 Forward Current Derating Curve** 



**Fig.2 Typical Junction Capacitance** 

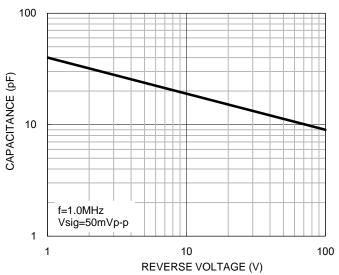
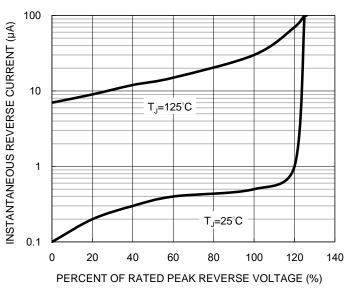
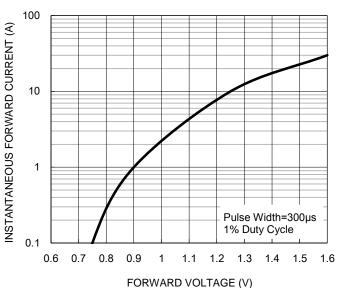


Fig.3 Typical Reverse Characteristics



**Fig.4 Typical Forward Characteristics** 



Version:L1705

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Fig.5 Maximum Non-repetitive Forward Surge Current

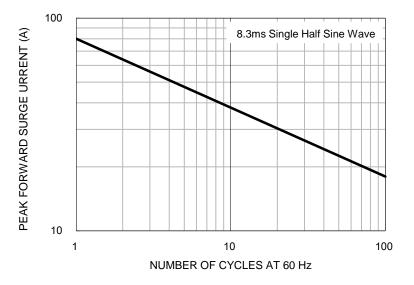
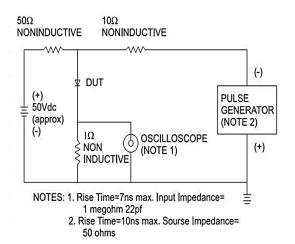
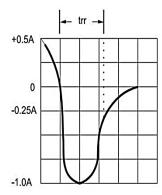


Fig.6 Reverse Recovery Time Characteristic And Test Circuit Diagram

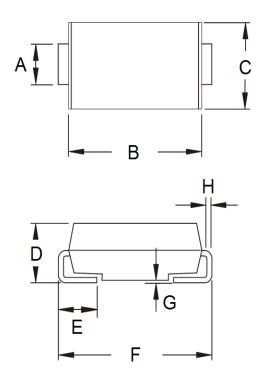






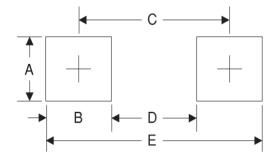
### **PACKAGE OUTLINE DIMENSIONS**

DO-214AA (SMB)



DIM.	Unit	(mm)	Unit (inch)		
DIIVI.	Min	Max	Min	Max	
Α	1.95	2.20	0.077	0.087	
В	4.05	4.60	0.159	0.181	
С	3.30	3.95	0.130	0.156	
D	1.95	2.65	0.077	0.104	
Е	0.75	1.60	0.030	0.063	
F	5.10	5.60	0.201	0.220	
G	0.05	0.20	0.002	0.008	
Н	0.15	0.31	0.006	0.012	

### **SUGGESTED PAD LAYOUT**



Symbol	Unit (mm)	Unit (inch)
A	2.3	0.091
В	2.5	0.098
С	4.3	0.169
D	1.8	0.071
Е	6.8	0.268

#### **MARKING DIAGRAM**



P/N = Marking Code
G = Green Compound
YW = Date Code
F = Factory Code





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S3BB M4G S3BBHM4G S3DB M4G S3DBHM4G S3AB M4G S3GBHM4G S3JB M4G S3JBHM4G S3ABHM4G S3KB M4G S3KBHM4G S3MBHM4G S3GB M4G